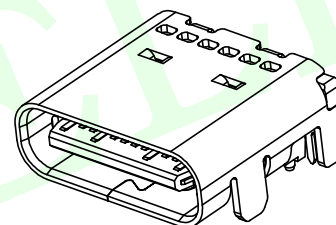
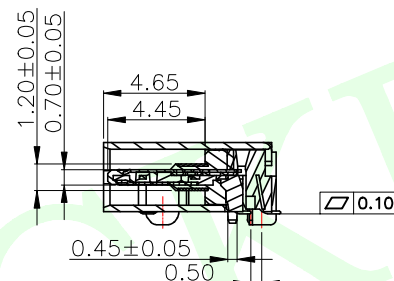
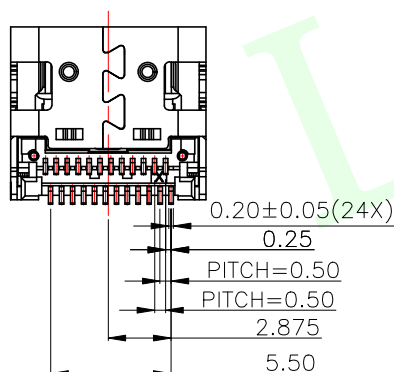
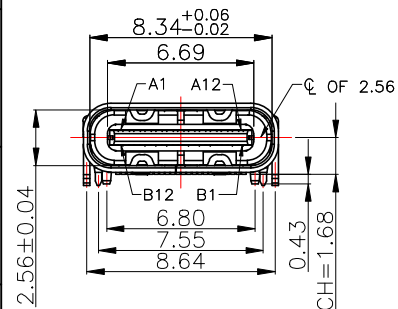


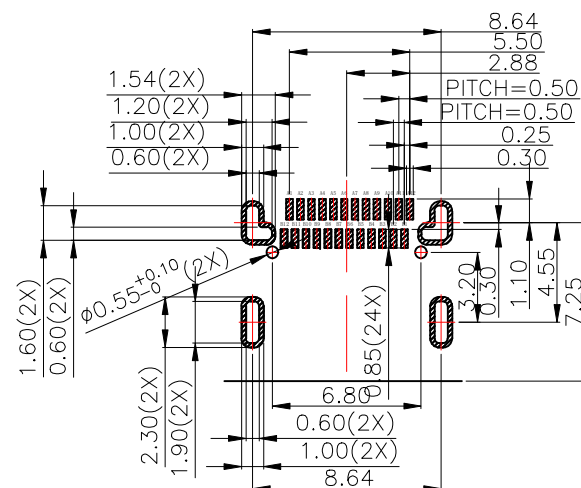
- 1. MATERIAL SPECIFICATION:
 - 1. HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0.
 - 2. CONTACTS: COPPER ALLOY
 - 3. MID PLATE: STAINLESS STEEL
 - 4. FRONT SHELL: STAINLESS STEEL
 - 5. EMI PLATE: STAINLESS STEEL
- 2. PLATING SPECIFICATION:
 - 2-1. CONTACTS:
 - Ni 50u" MIN. UNDER PLATED OVER ALL.
 - Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
 - (GOLD PLATING THICKNESS FOLLOW THE P/N)
 - PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
 - 2-2. FRONT SHELL:
 - Ni 30u" MIN. UNDER PLATED OVER ALL.
 - 2-3. MID PLATE:
 - Ni 30u" MIN. UNDER PLATED OVER ALL.
 - Sn 80u" MIN. PLATED OVER ALL
 - 2-4. EMI PLATE:
 - CLEAR ONLY
- 3. MECHANICAL PERFORMANCE,
 - 3-1. INSERTION FORCE: 0.5~2.0kgf.
 - 3-2. REMOVAL FORCE: 0.8kgf~2.0kgf.
 - 3-3. DURABILITY: 10000 CYCLES.
- 4. ELECTRICAL PERFORMANCE,
 - 4-1. CURRENT RATING: 5.0A
VOLTAGE RATING: 5.0V
 - 4-2. LLCR:
 - VBUS & GND PINS AND OTHER PINS: 40ma/PIN MAX.
 - LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
 - 4-3. INSULATION RESISTANCE: 100MΩ MIN
 - 4-4. DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
- 5. ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -25°C~+85°C.
- 6. IR REFLOW:
 - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.



SECTION:A-A



PIN NUMBER	SIGNAL NAME	PIN NUMBER	SIGNAL NAME
A1	GND	B12	GND
A2	TXp1	B11	RXp1
A3	TXn1	B10	RXn1
A4	Vbus	B9	Vbus
A5	CC1	B8	SBUS2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBUS1	B5	CC2
A9	Vbus	B4	Vbus
A10	RXn2	B3	TXn2
A11	RXp2	B2	TXp2
A12	GND	B1	GND



RECOMMENDED PCB LAYOUT(TOP VIEW)

THICKNESS 0.60MM:DEFAULT TOLERANCE:±0.05

LCK-TCF 915 - LXXX Y L- G3
 联晟欣 LCK
 产品类别 TCF: TYPE C母头
 TCM: TYPE C公头
 产品流水料号识别码
 壳长 L79: 7.9
 电镀规格 G1: 1U
 G3: 3U
 (以此类推)
 包装方式 L: 圆盘
 B: 吸塑盒
 T: 管装
 Y: 有柱
 W: 无柱

QUADRANT POINT	Ⓚ	 联晟欣连接器（深圳）有限公司 Lianshengxin Connector (Shenzhen) Co., Ltd
TANGENCY POINT	Ⓣ	
INTERSECTION POINT	Ⓜ	
UNLESS OTHERWISE SPECIFIED, TOLERANCE:		
X.	±0.25	
X.x	±0.20	
X.xx	±0.15	
ANGULAR	±3°	